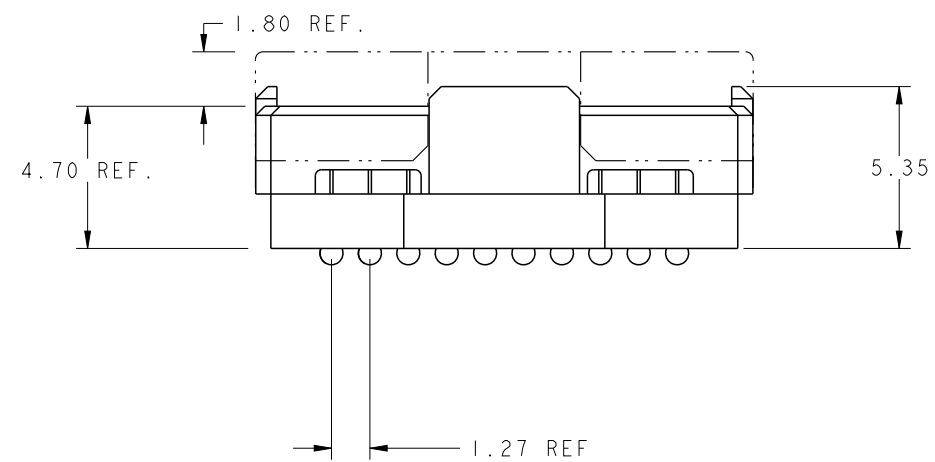
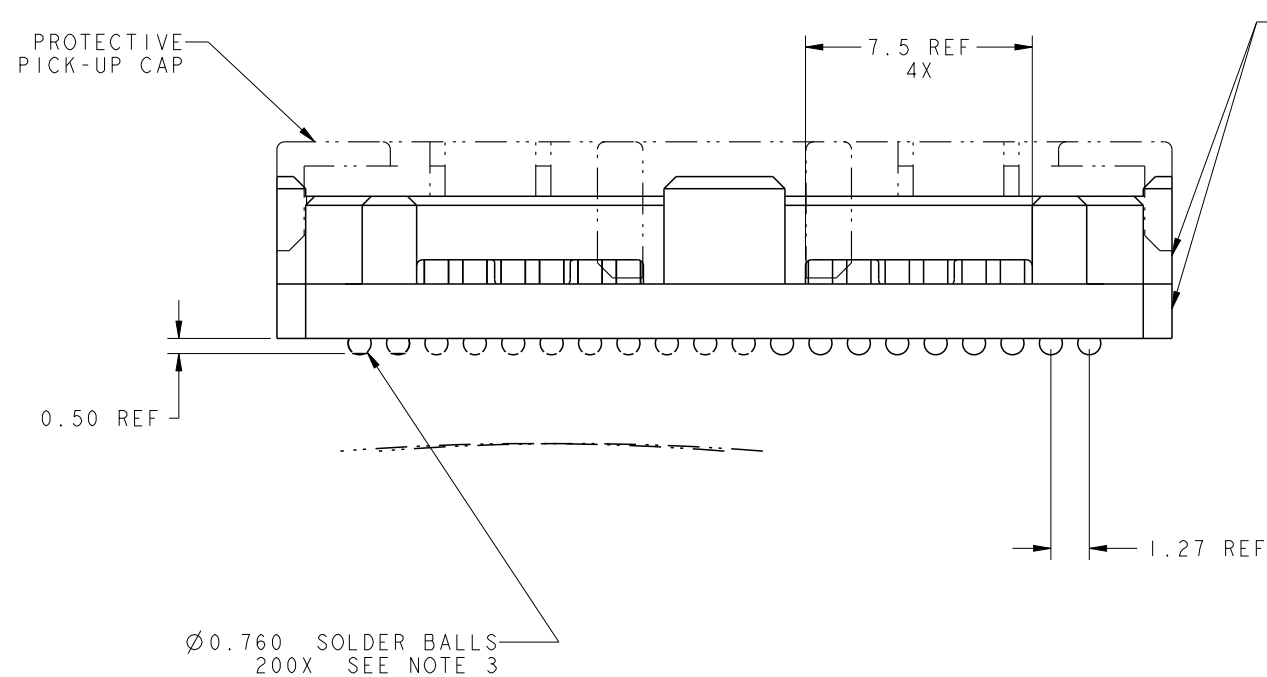
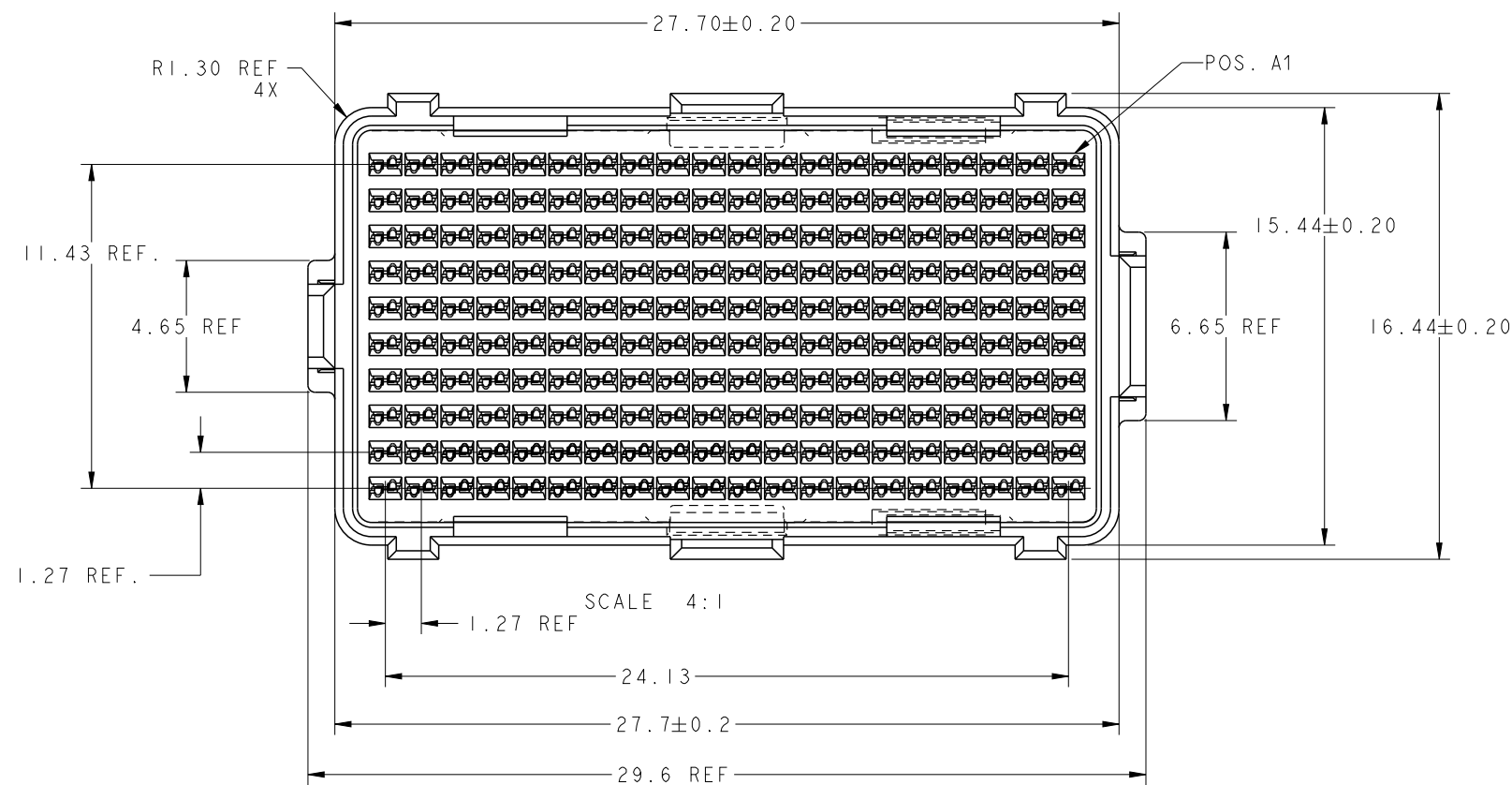


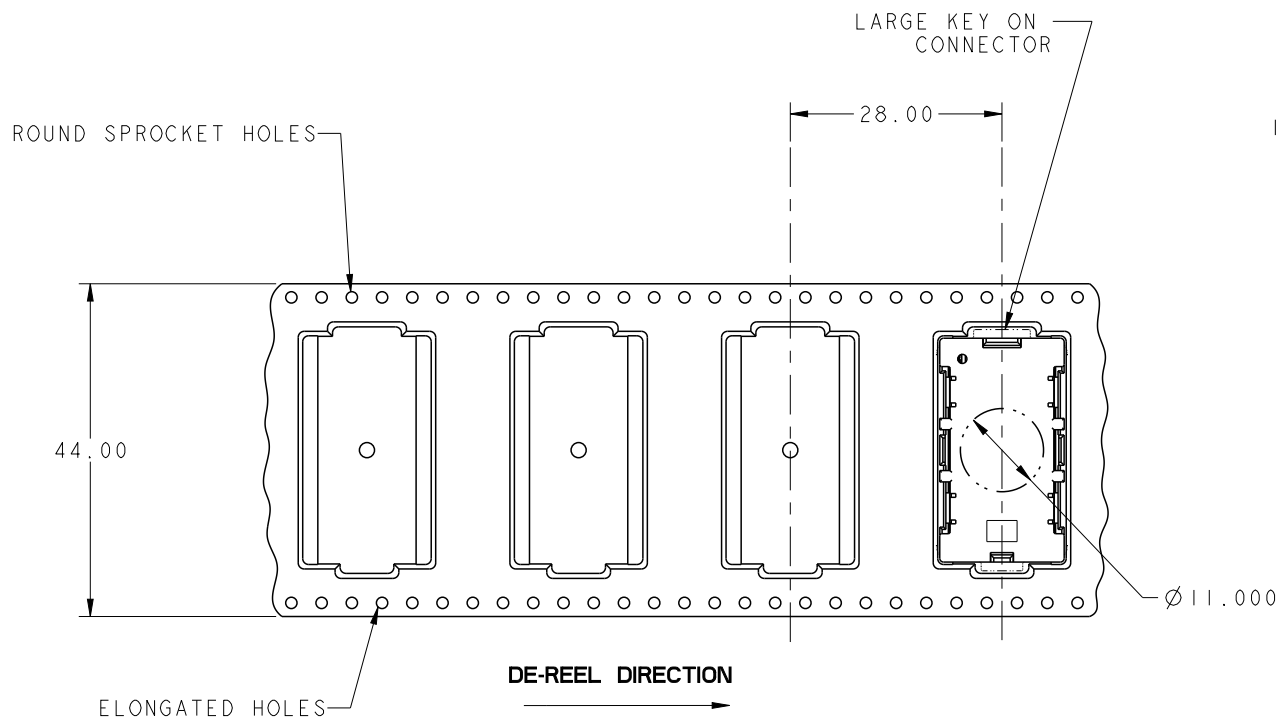
PRODUCT NUMBER: SEE SHEET 2



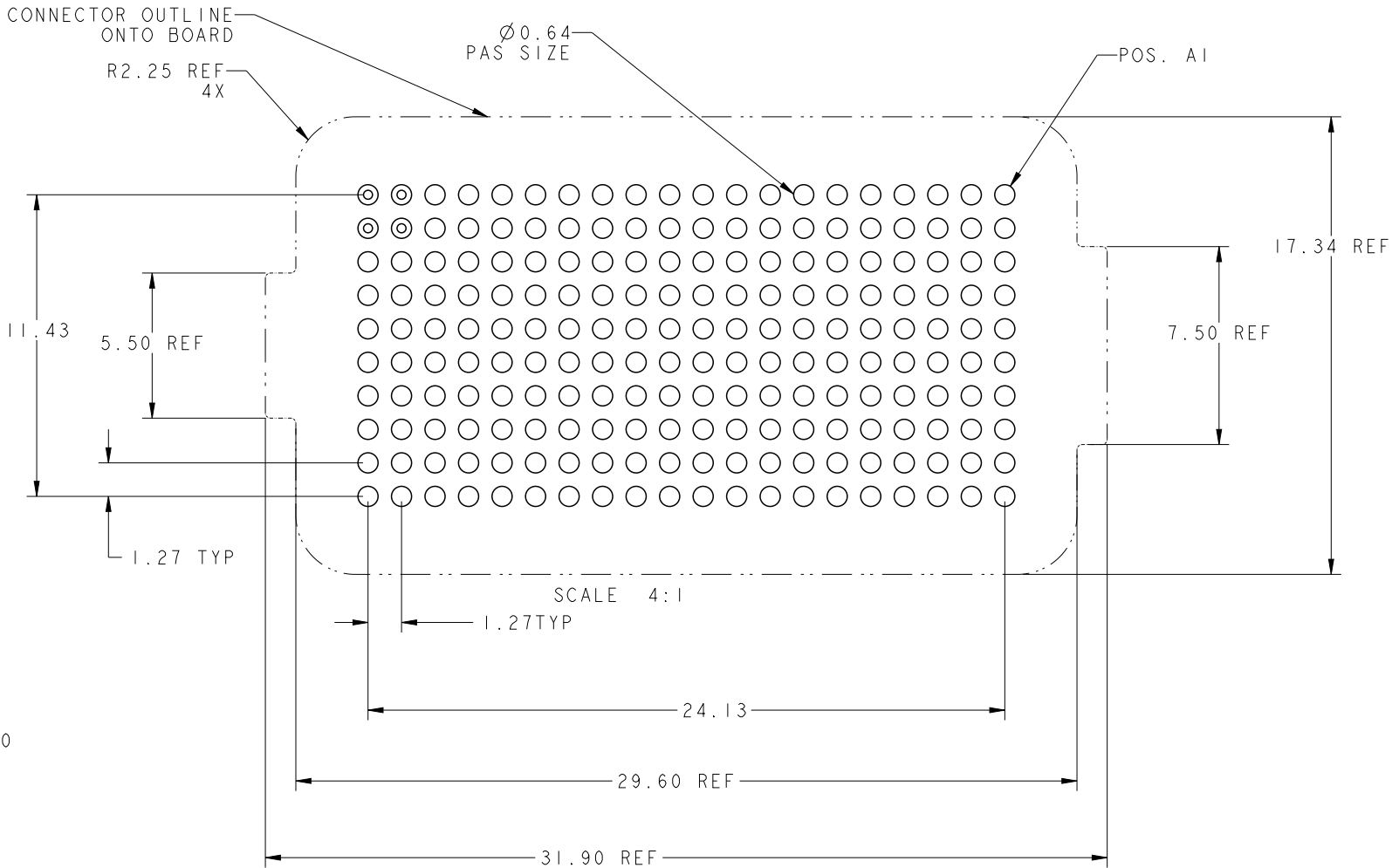
Ø0.760 SOLDER BALLS
200X SEE NOTE 3

spec ref				dr		w wadmin	2001/08/01	projection	mm	size	A3	scale	2:1			
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng		Dave Horchler	2013/01/22					ecn no			ELX-V-13917-1	
				chr		-	-					rel level			Released	
				appr		R Marshall	2013/01/22									
								product family		MEG-ARRAY						
surface	linear	0.X		±.3			title		6.0mm RECPT. ASSY		dwg no		55724		rev	J
		0.XX		±.10												
		0.XXX		±.050												
	angular	0°		±°		www.fci.com		cat. no.		Product - Customer Drw			sheet 1 of 3			

PRODUCT NO.	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
55724-001	YES	15u" (.38um) Au OVER Ni	SnPb
55724-001LF	YES	15u" (.38um) Au OVER Ni	SnAgCu LEAD FREE 6 7
55724-091	YES	15u" (.38um) GXT OVER Ni	SnPb
55724-091LF	YES	15u" (.38um) GXT OVER Ni	SnAgCu LEAD FREE 6 7
55724-101	YES	30u" (.76um) Au OVER Ni	SnPb
55724-101LF	YES	30u" (.76um) Au OVER Ni	SnAgCu LEAD FREE 6 7
55724-191	YES	30u" (.76um) GXT OVER Ni	SnPb
55724-191LF	YES	30u" (.76um) GXT OVER Ni	SnAgCu LEAD FREE 6 7
55724-201	YES	50u" (1.27um) Au OVER Ni	SnPb
55724-201LF	YES	50u" (1.27um) Au OVER Ni	SnAgCu LEAD FREE 6 7
55724-291	YES	50u" (1.27um) GXT OVER Ni	SnPb
55724-291LF	YES	50u" (1.27um) GXT OVER Ni	SnAgCu LEAD FREE 6 7



TAPE & REEL PACKAGING
PER EIA 481-3



BOARD PATTERN

spec ref	dr	wcadmin	2001/08/01	projection	mm	size	A3	scale	2:1
tolerance std	eng	Dave Horchler	2013/01/22	chr	-	ecm no	ELX-V-13917-1	rel level	Released
surface	appr	R Marshall	2013/01/22	product family	MEG-ARRAY	dwg no	55724	rev	J
linear	0.X	±.3	FCI	6.0mm RECPT. ASSY	cat. no.	Product - Customer Drw	sheet 2 of 3		
0.XX	±.10								
0.XXX	±.050								
angular	0°	±°							

NOTES:

1. MATERIAL:
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING CONTACT: SEE TABLE ON SHEET 1
SOLDER BALL: SEE TABLE ON SHEET 1
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

2. PLATING FOR -2XX SERIES DASH NOS:
Au OVER Ni WITH SPECIAL CONTACT
GEOMETRY TO MEET REQUIREMENTS
OF TELCORDIA GR-1217-CORE:
CENTRAL OFFICE ENVORONMENT.

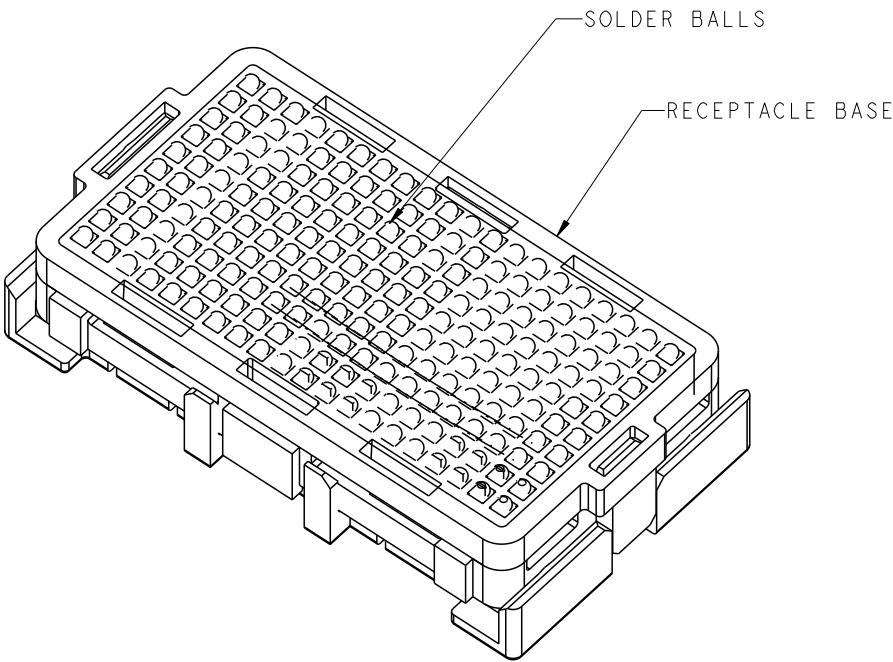
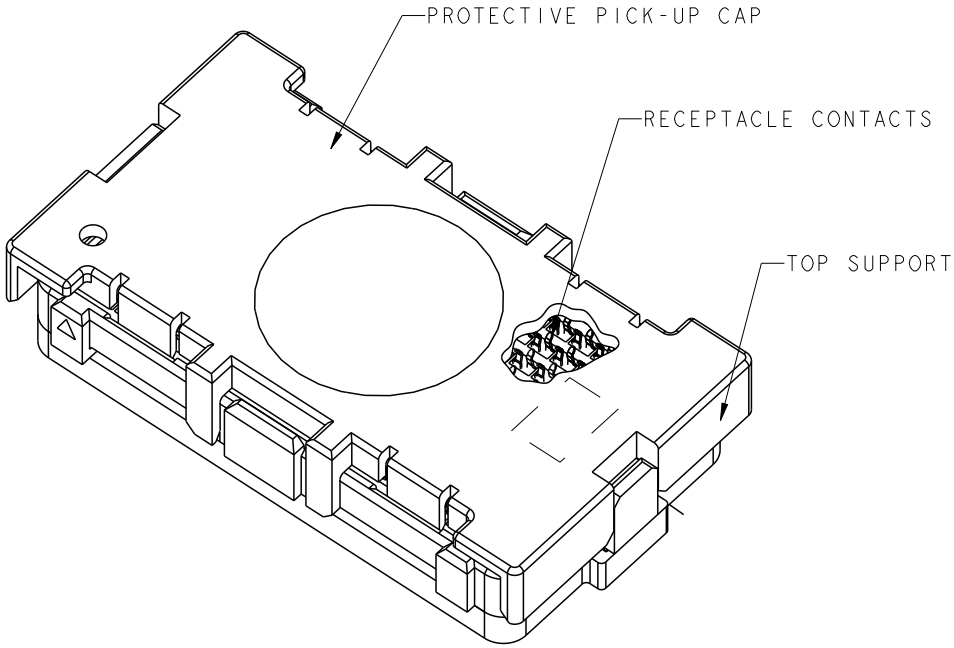
3. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE
DUE TO REFLOW ATTACHMENT.

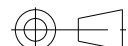
4. OVERALL BOARD-TO-BOARD STACK
HEIGHT WHEN MATED TO:
200 POSITION 0.0mm PLUG (84516) IS 6.0 REF.
200 POSITION 6.0mm PLUG (84530) IS 12.0 REF.

5. SEE SK-47284 FOR MATING RESTRICTIONS
WITH EARLIER DESIGN VERSIONS.

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION
GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY
IN A LEADED SOLDER PROSESS DUE TO A HIGHER REFLOW TEMPERATURE
LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH
LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI
FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVE AND OTHER
COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004. PRODUCT
MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE
NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH
CHARACTER POSITION



spec ref				dr		w cadmin	2001/08/01		projection		mm		size		A3	scale		1:1									
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED				eng		Dave Horchler		2013/01/22						ecn no		ELX-V-13917-1									
						chr		-		-																	
						appr		R Marshall		2013/01/22						product family				MEG-ARRAY				rel level		Released	
surface 		linear		0.X		±.3				title		6.0mm RECPT. ASSY						dwg no		55724				rev		J	
				0.XX		±.10																					
				0.XXX		±.050																					
		angular		0°		±°		www.fci.com		cat. no.		Product - Customer Drw						sheet 3 of 3									



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